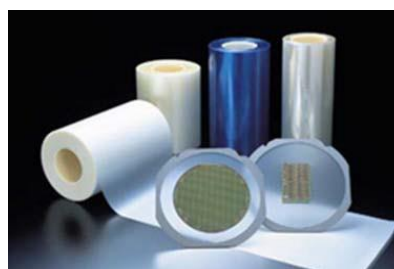
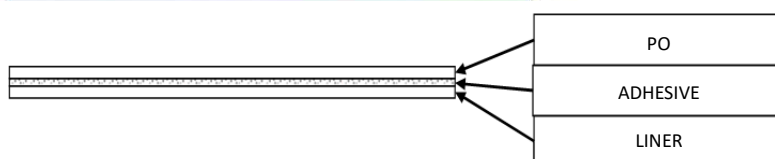


## Dicing Tape (UV series)

### DESCRIPTION

High technology is required to a dicing tape with the developments of diversified chips with high quality, in accordance with requirements of each type of workpiece. Elegrip dicing tapes produced by Ds are widely used for dicing and singulation of driver ICs, LTCC substrates, EMC package substrates, Si wafers, ceramics, glass,

### STRUCTURE



### CHARACTERISTICS

Item		Unit	Value
Width		mm	300
Length		M	100
Thickness	Liner Thickness	μm	30± 3
	Adhesive Thickness	μm	15± 2
	PO Thickness	μm	100± 3
	Total Thickness	μm	145± 8
Adhesion	Adhesion	g/25 mm	1300± 200
	Adhesion after UV.	g/25 mm	35± 15

UV exposure : 460 mJ/cm<sup>2</sup>

### ADVANTAGE

- Excellent control to back-side chipping and chip fly-off.
- Excellent adhesiveness.
- Smooth peeling by UV.
- High performance to EMC (Epoxy Mold Compound) and other types of difficult-to-adhere workpiece.
- Easy to release for next process
- Produce in 1000 class clean room